

PMEG060T080CLPE

60 V, 2 x 4 A dual common cathode low leakage current Trench Schottky barrier rectifier

15 July 2024

Product data sheet

1. General description

Trench dual Schottky barrier rectifier in common cathode configuration encapsulated in a CFP15B (SOT1289B) power and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Reverse voltage: V_R ≤ 60 V
- Forward current: I_F ≤ 4 A (per diode)
- Low forward voltage
- · Low leakage current due to Trench Schottky technology
- Power and flat lead SMD plastic package
- Package height typical 0.95 mm
- · High power capability due to clip-bond technology

3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- · Switch mode power supply
- · Reverse polarity protection
- · Low power consumption applications
- · Freewheeling applications

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Per diode (u	nless otherwise specif	fied)	'	'	_		
I _{F(AV)}	average forward current	δ = 0.5; f = 20 kHz; square wave; $T_{sp} \le$ 160 °C		-	-	4	А
V_R	reverse voltage	T _j = 25 °C		-	-	60	V
V _F	forward voltage	I _F = 4 A; T _j = 25 °C	[1]	-	580	660	mV
I _R	reverse current	V _R = 10 V; T _j = 25 °C	[1]	-	0.14	0.9	μA
İ		V _R = 60 V; T _j = 25 °C	[1]	-	0.3	1.8	μA

[1] Very short pulse, in order to maintain a stable junction temperature.



5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode (diode 1)		CC
2	A2	anode (diode 2)		
3	CC	common cathode	3 [
			CFP15B (SOT1289B)	A1 A2
				006aab034

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG060T080CLPE		plastic, thermal enhanced ultra thin SMD package; 3 leads; 2.13 mm pitch; 5.8 x 4.3 x 0.95 mm body	<u>SOT1289B</u>

7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG060T080CLPE	060T
	L08C

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC60134).

Parameter	Conditions		Min	Max	Unit
ess otherwise specified)				•	
reverse voltage	T _j = 25 °C		-	60	V
forward current	δ = 1; T _{sp} ≤ 156 °C		-	5.7	Α
average forward current	δ = 0.5; f = 20 kHz; square wave; T _{sp} ≤ 160 °C		-	4	А
non-repetitive peak forward current	t_p = 8.3 ms; half sine wave; $T_{j(init)}$ = 25 °C		-	80	Α
	t _p = 8.3 ms; half sine wave; per device; T _{j(init)} = 25 °C		-	150	Α
e diode loaded		•		•	
total power dissipation	T _{amb} ≤ 25 °C	[1]	-	1.66	W
		[2]	-	2.15	W
junction temperature			-	175	°C
ambient temperature			-55	175	°C
storage temperature			-65	175	°C
	reverse voltage forward current average forward current non-repetitive peak forward current e diode loaded total power dissipation junction temperature ambient temperature	reverse voltage $T_j = 25 ^{\circ}\text{C}$ forward current $\delta = 1$; $T_{sp} \leq 156 ^{\circ}\text{C}$ average forward current $\delta = 0.5$; $f = 20 \text{kHz}$; square wave; $T_{sp} \leq 160 ^{\circ}\text{C}$ non-repetitive peak forward current $\delta = 0.5$;	reverse voltage $T_{j} = 25 ^{\circ}\text{C}$ forward current $\delta = 1$; $T_{sp} \leq 156 ^{\circ}\text{C}$ average forward current $\delta = 0.5$; $f = 20 \text{kHz}$; square wave; $T_{sp} \leq 160 ^{\circ}\text{C}$ non-repetitive peak forward current $t_{p} = 8.3 \text{ms}$; half sine wave; $T_{j(\text{init})} = 25 ^{\circ}\text{C}$ $t_{p} = 8.3 \text{ms}$; half sine wave; per device; $T_{j(\text{init})} = 25 ^{\circ}\text{C}$ e diode loaded $t_{p} = 0.3 \text{ms}$ total power dissipation $t_{p} = 0.3 \text{ms}$ for $t_{p} = 0.3 \text{ms}$ for $t_{p} = 0.3 \text{ms}$ and $t_{p} = 0.3 \text{ms}$ for $t_{p} = 0.3 \text{ms}$; half sine wave; per device; $t_{p} = 0.3 \text{ms}$ for $t_{p} = 0.3 \text{ms}$ f	reverse voltage $T_j = 25 ^{\circ}\text{C}$ - forward current $\delta = 1$; $T_{sp} \leq 156 ^{\circ}\text{C}$ - average forward current $\delta = 0.5$; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $T_{sp} \leq 0.5$; $T_{sp} \approx 0.$	reverse voltage $T_j = 25 ^{\circ}\text{C}$ - 60 forward current $\delta = 1$; $T_{sp} \le 156 ^{\circ}\text{C}$ - 5.7 average forward current $\delta = 0.5$; $f = 20 \text{kHz}$; square wave; $T_{sp} \le 160 ^{\circ}\text{C}$ - 80 non-repetitive peak forward current $t_p = 8.3 \text{ms}$; half sine wave; $t_{j(\text{init})} = 25 ^{\circ}\text{C}$ - 80 forward current $t_p = 8.3 \text{ms}$; half sine wave; per device; $t_{j(\text{init})} = 25 ^{\circ}\text{C}$ - 150 redicted loaded $t_{j(\text{init})} = 25 ^{\circ}\text{C}$ - 1.66 redicted power dissipation $t_{j(\text{init})} = 25 ^{\circ}\text{C}$ - 1.75 ambient temperature - 1.75 redicted $t_{j(\text{init})} = 25 ^{\circ}\text{C}$ redicted $t_{j(\text{init})} = 25 ^$

^[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

^[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
	e diode loaded			1	- 7 P		
rei device, oii	e diode ioaded						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	90	K/W
			[1] [3]	-	-	70	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[4]	-	-	7	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [4] Soldering point of cathode tab.

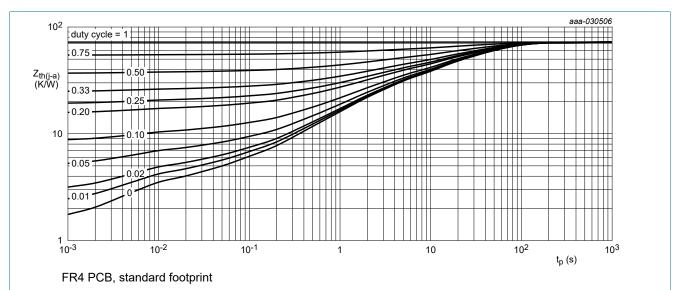


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

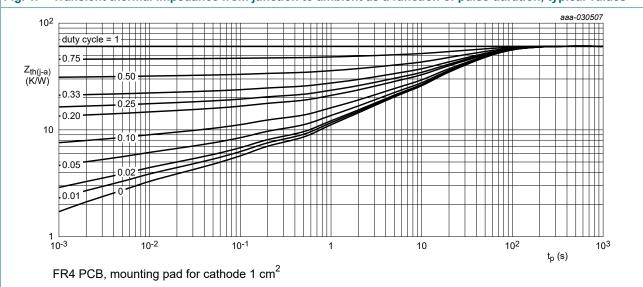


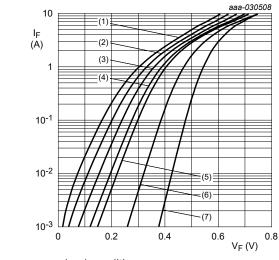
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Per diode (ı	unless otherwise specified	1)					
$V_{(BR)R}$	reverse breakdown voltage	I _R = 1 mA; T _j = 25 °C	[1]	60	-	-	V
V _F	forward voltage	I _F = 0.5 A; T _j = 25 °C	[1]	-	440	510	mV
		I _F = 1 A; T _j = 25 °C	[1]	-	470	540	mV
		I _F = 4 A; T _j = 25 °C	[1]	-	580	660	mV
		I _F = 4 A; T _j = -40 °C	[1]	-	630	720	mV
		I _F = 4 A; T _j = 125 °C	[1]	-	520	610	mV
I _R	reverse current	V _R = 10 V; T _j = 25 °C	[1]	-	0.14	0.9	μA
		V _R = 40 V; T _j = 25 °C	[1]	-	0.18	1.2	μΑ
		V _R = 60 V; T _j = 25 °C	[1]	-	0.3	1.8	μΑ
		V _R = 60 V; T _j = 125 °C	[1]	-	0.5	3	mA
C _d	diode capacitance	V _R = 1 V; f = 1 MHz; T _j = 25 °C		-	560	-	pF
		$V_R = 10 \text{ V}; f = 1 \text{ MHz}; T_j = 25 ^{\circ}\text{C}$		-	180	-	pF
t _{rr}	reverse recovery time step recovery	$I_F = 0.5 \text{ A}; I_R = 0.5 \text{ A}; I_{R(meas)} = 0.1 \text{ A};$ $T_j = 25 \text{ °C}$		-	17	-	ns
	reverse recovery time ramp recovery	$dI_F/dt = 200 \text{ A/}\mu\text{s}; I_F = 6 \text{ A}; V_R = 26 \text{ V};$ $T_j = 25 ^{\circ}\text{C}$		-	11	-	ns
V_{FRM}	peak forward recovery voltage	$I_F = 0.5 \text{ A}; dI_F/dt = 20 \text{ A/}\mu\text{s}; T_j = 25 ^{\circ}\text{C}$		-	460	-	mV

^[1] Very short pulse, in order to maintain a stable junction temperature.



pulsed condition

(1) $T_i = 175$ °C

(2) $T_i = 150 °C$

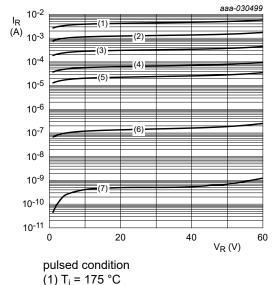
(3) $T_i = 125 °C$

 $(4) T_i = 100 °C$

 $(5) T_i = 85 ^{\circ}C$

(6) $T_i = 25 \,^{\circ}\text{C}$ $(7) T_i = -40 ^{\circ}C$

Fig. 3. Forward current as a function of forward voltage; typical values



 $(2) T_i = 150 ^{\circ}C$

(3) $T_i = 125 °C$

 $(4) T_i = 100 °C$

 $(5) T_i = 85 ^{\circ}C$ (6) $T_i = 25 \,^{\circ}\text{C}$

 $(7) T_i = -40 ^{\circ}C$

Fig. 4. Reverse current as a function of reverse voltage; typical values

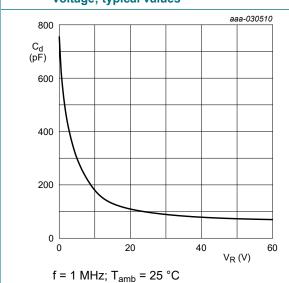
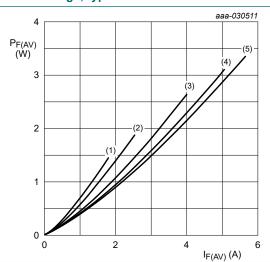


Fig. 5. Diode capacitance as a function of reverse voltage; typical values



T_i = 100 °C

 $(1) \delta = 0.1$

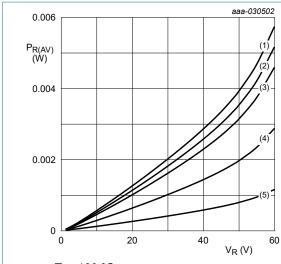
(2) $\delta = 0.2$

 $(3) \delta = 0.5$

 $(4) \delta = 0.8$

(5) $\delta = 1$; DC

Average forward power dissipation as a Fig. 6. function of average forward current; typical values



 $T_j = 100 \,^{\circ}C$

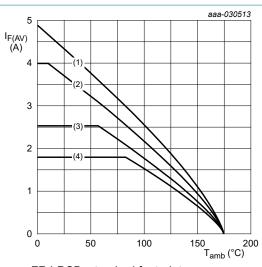
 $(1) \delta = 1; DC$

 $(2) \delta = 0.9$

 $(3) \delta = 0.8$ $(4) \delta = 0.5$

 $(5) \delta = 0.2$

Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

T_i = 175 °C

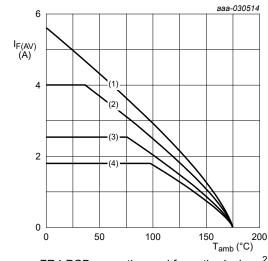
 $(1) \delta = 1$; DC

(2) $\delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 8. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm²

 $T_j = 175 \,{}^{\circ}\text{C}$

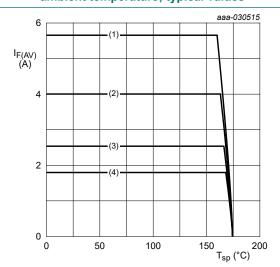
(1) $\delta = 1$; DC

(2) $\delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



 $T_i = 175 \,{}^{\circ}\text{C}$

 $(1) \delta = 1; DC$

(2) $\delta = 0.5$; f = 20 kHz

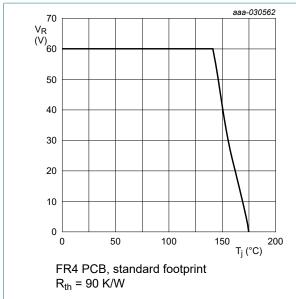
(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 10. Average forward current as a function of solder point temperature; typical values

aaa-030563

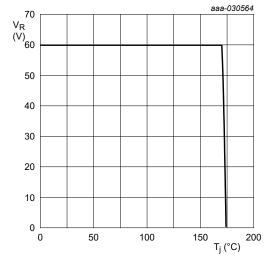
60 V, 2 x 4 A dual common cathode low leakage current Trench Schottky barrier rectifier



70 (V) (O) 50 40 30 20 10 50 100 150 FR4 PCB, mounting pad for cathode 1 cm² $R_{th} = 70 \text{ K/W}$

of junction temperature; typical values

Fig. 11. Derated maximum reverse voltage as a function | Fig. 12. Derated maximum reverse voltage as a function of junction temperature; typical values



Soldering point of cathode tab $R_{th} = 7 \text{ K/W}$

Fig. 13. Derated maximum reverse voltage as a function of junction temperature; typical values

11. Test information

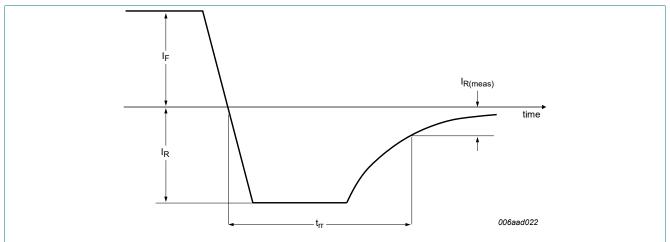


Fig. 14. Reverse recovery definition; step recovery

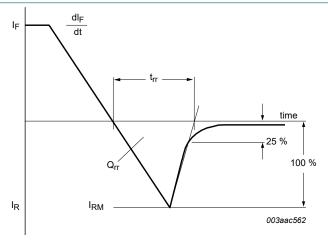


Fig. 15. Reverse recovery definition; ramp recovery

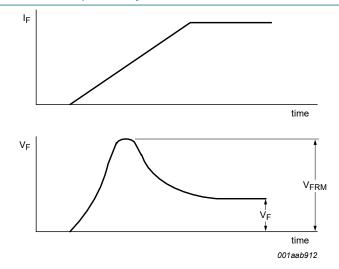
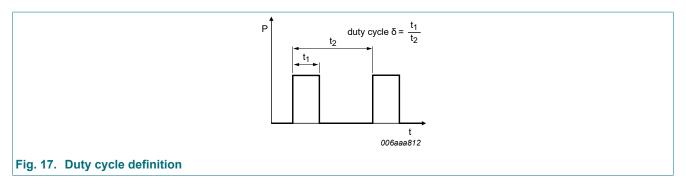


Fig. 16. Forward recovery definition



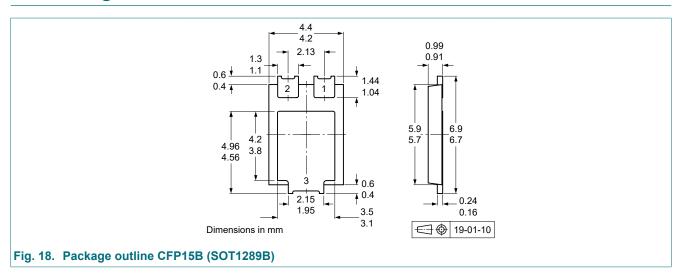
The current ratings for the typical waveforms are calculated according to the equations:

 $I_{F(AV)}$ = $I_M \times \delta$ with I_M defined as peak current

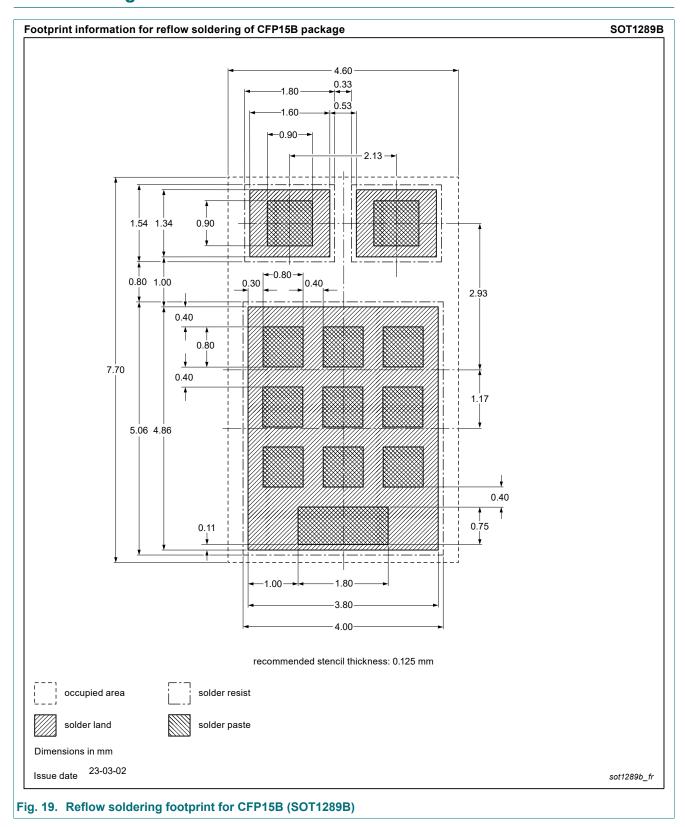
 $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_{M} \times \sqrt{\delta}$

with $I_{\mbox{\scriptsize RMS}}$ defined as RMS current.

12. Package outline



13. Soldering



14. Revision history

Table 8. Revision history

rable of revision mistory						
Data sheet ID	Release date	Data sheet status	Change notice	Supersedes		
PMEG060T080CLPE v.4	20240715	Product data sheet	-	PMEG060T080CLPE v.3		
Modifications:	Reflow soldering footprint: Stencil design for solder paste printing changed.					
PMEG060T080CLPE v.3	20230401	Product data sheet	-	PMEG060T080CLPE v.2		
PMEG060T080CLPE v.2	20200427	Product data sheet	-	PMEG060T080CLPE v.1		
PMEG060T080CLPE v.1	20200304	Objective data sheet	-	-		

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at https://www.nexperia.com.

Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. Nexperia does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local Nexperia sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

Product specification — The information and data provided in a Product data sheet shall define the specification of the product as agreed between Nexperia and its customer, unless Nexperia and customer have explicitly agreed otherwise in writing. In no event however, shall an agreement be valid in which the Nexperia product is deemed to offer functions and qualities beyond those described in the Product data sheet.

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, Nexperia does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. Nexperia takes no responsibility for the content in this document if provided by an information source outside of Nexperia.

In no event shall Nexperia be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, Nexperia's aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of Nexperia.

Right to make changes — Nexperia reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — Nexperia products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of an Nexperia product can reasonably be expected to result in personal

injury, death or severe property or environmental damage. Nexperia and its suppliers accept no liability for inclusion and/or use of Nexperia products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Quick reference data — The Quick reference data is an extract of the product data given in the Limiting values and Characteristics sections of this document, and as such is not complete, exhaustive or legally binding.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. Nexperia makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using Nexperia products, and Nexperia accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the Nexperia product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

Nexperia does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using Nexperia products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). Nexperia does not accept any liability in this respect.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and (proper) operation of the device at these or any other conditions above those given in the Recommended operating conditions section (if present) or the Characteristics sections of this document is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

Terms and conditions of commercial sale — Nexperia products are sold subject to the general terms and conditions of commercial sale, as published at http://www.nexperia.com/profile/terms, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. Nexperia hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of Nexperia products by customer.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

Non-automotive qualified products — Unless this data sheet expressly states that this specific Nexperia product is automotive qualified, the product is not suitable for automotive use. It is neither qualified nor tested in accordance with automotive testing or application requirements. Nexperia accepts no liability for inclusion and/or use of non-automotive qualified products in automotive equipment or applications.

In the event that customer uses the product for design-in and use in automotive applications to automotive specifications and standards, customer (a) shall use the product without Nexperia's warranty of the product for such automotive applications, use and specifications, and (b) whenever customer uses the product for automotive applications beyond Nexperia's specifications such use shall be solely at customer's own risk, and (c) customer fully indemnifies Nexperia for any liability, damages or failed product claims resulting from customer design and use of the product for automotive applications beyond Nexperia's standard warranty and Nexperia's product specifications.

Translations — A non-English (translated) version of a document is for reference only. The English version shall prevail in case of any discrepancy between the translated and English versions.

Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

PMEG060T080CLPE

Contents

1.	General description	1
2.	Features and benefits	1
3.	Applications	1
4.	Quick reference data	1
5.	Pinning information	2
6.	Ordering information	2
7.	Marking	2
8.	Limiting values	3
9.	Thermal characteristics	4
10.	Characteristics	5
11.	Test information	9
12.	Package outline	. 10
	Soldering	
14.	Revision history	12
	Legal information	

For more information, please visit: http://www.nexperia.com For sales office addresses, please send an email to: salesaddresses@nexperia.com Date of release: 15 July 2024

[©] Nexperia B.V. 2024. All rights reserved

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Nexperia:

PMEG060T080CLPEZ